

**ABSTRACT OF THE DISCLOSURE**

5           A method of reducing package stress includes placing  
matched components of an op-amp substantially in a region  
of a die having the least stress gradients. The region is  
located in the center of the die. Further, the center is  
the common centroid of the die. The matched components are  
10 the current mirror input stages of the op-amp. In one  
embodiment, a semiconductor configuration includes a die  
having a region with the least stress gradients, and an op-  
amp containing matched components that are located  
substantially in the region.

15